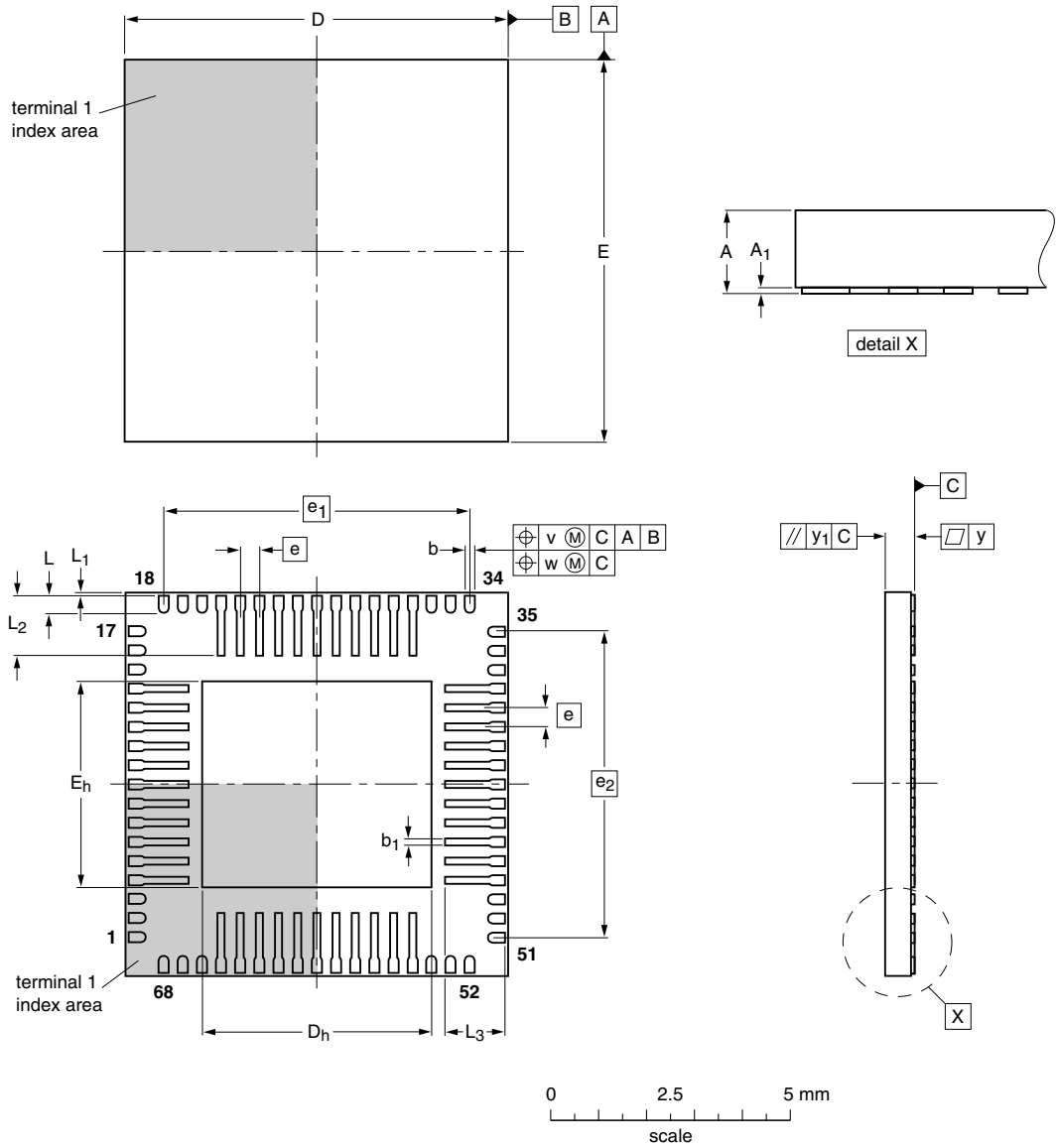
HUQFN68U: plastic thermal enhanced ultra thin quad flat package; no leads; 68 terminals; UTLP based; body 8 × 8 × 0.55 mm **SOT943-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max	A_1	b	b_1	D	D_h	E	E_h	e	e_1	e_2	L	L_1	L_2	L_3	v	w	y	y_1
mm	0.6	0.05 0.00	0.25 0.15	0.2 0.1	8.1 7.9	4.95 4.65	8.1 7.9	4.45 4.15	0.4	6.4	6.4	0.40 0.25	0.10 0.05	1.55 1.40	1.30 1.15	0.1	0.05	0.05	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT943-1	- - -	- - -	- - -			~~06-10-18~~ 07-11-14

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